



*"The Inspection & Rework Specialists"*

## For Immediate Release

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**Note to Editors:** Supporting product photos (300dpi / knocked out / PSD) and MS Word text files may be downloaded from the FocalSpot website, URL: <http://www.focalspot.com/pr.htm>

### **Verifier WLP Automated Inspection Solution for Quality Verification of Wafer Level Packages on Tape-&-Reel**

**San Diego, California (July 17, 2007)** – FocalSpot, Inc ([www.focalspot.com](http://www.focalspot.com)), a premiere provider of affordable high-quality BGA/SMT inspection and rework solutions to the SMT electronics manufacturing industry, today announced the unveiling of their automated x-ray inspection system at SEMICON West 2007 (West Hall - Level 2, Booth #8820) San Jose, California. The Verifier WLP is designed to address Wafer Level Package quality control for semiconductor package manufactures and tape-&-reel service providers.

The Verifier WLP is a portable inspection system that incorporates a tape-&-reel indexing mechanism to position wafer level packages for inspection automatically. The inspection process is able to detect otherwise invisible bottom-side package features such as: presence/absence of bumps, bridging, placement, bump diameter, pitch, and internal voids. The system can also be configured with a vision camera to provide complementary top-side, bottom-side and inter-package inspection to achieve 100% quality assurance of WLP tape-&-reel packages.

"FocalSpot, has worked closely with a leading provider of full service automated semiconductor packaging, to develop an automated quality assessment solution for WLP components on tape-&-reel," said Frank Silva, FocalSpot Vice President of Sales. By using a standard tape-&-reel indexing system the Verifier WLP is capable of 100% inspection with an inspection beat rate of ~28,000 parts/hr. Until now, semiconductor packaging service companies have only been able to perform top-side inspection using optical systems which are not capable of (inner package) bump verification — this is now made possible with the Verifier WLP," continued Mr. Silva.

#### **About FocalSpot, Inc.**

FocalSpot, Inc. is a provider of affordable high-quality BGA/SMT inspection and rework solutions to the electronics manufacturing industry worldwide.

For more information, visit [www.focalspot.com](http://www.focalspot.com), email [sales@focalspot.com](mailto:sales@focalspot.com), or call (858) 536.5050.

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